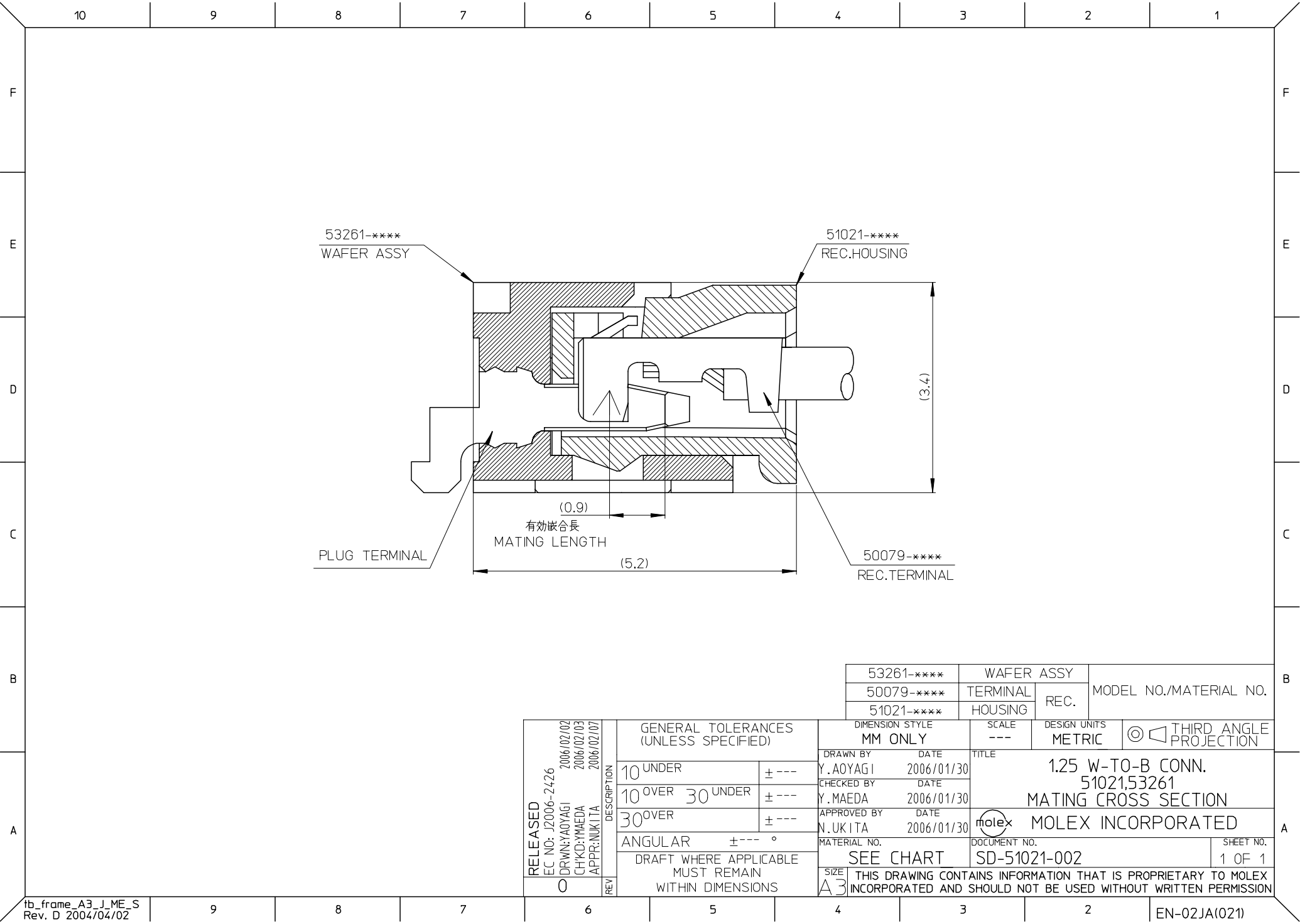
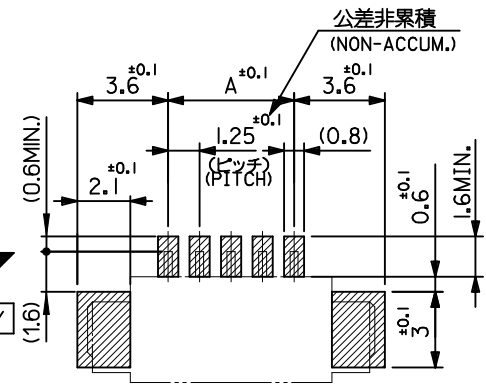
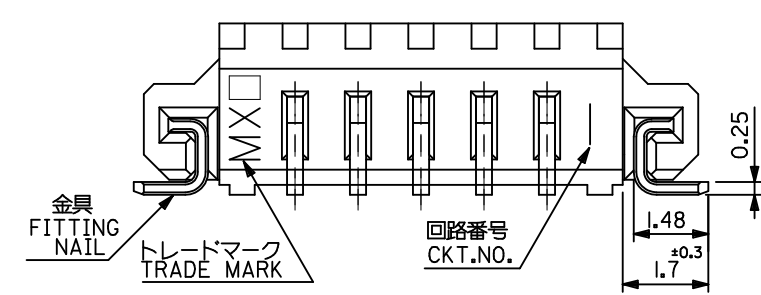
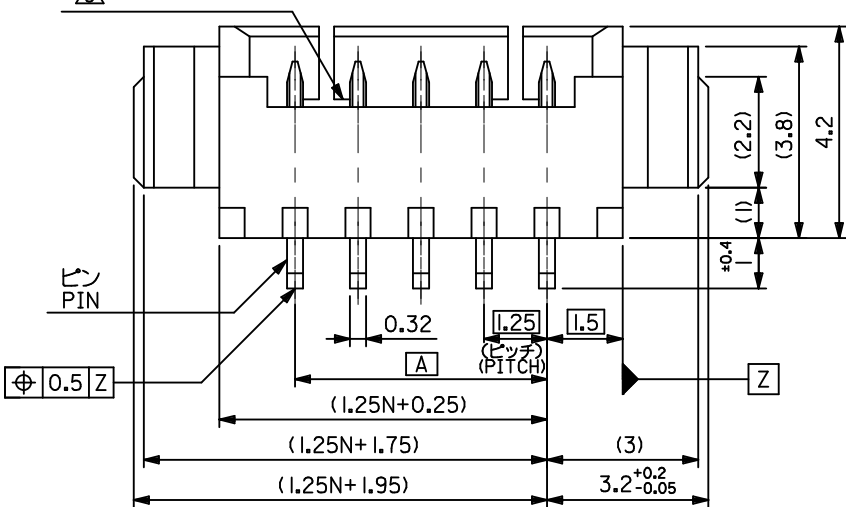
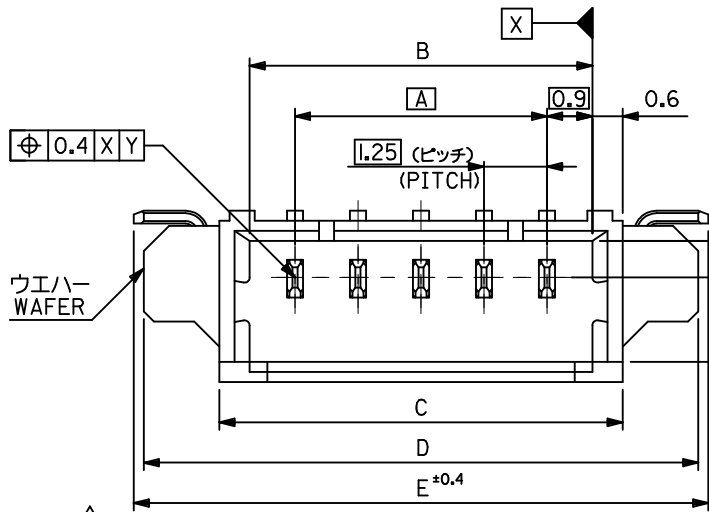


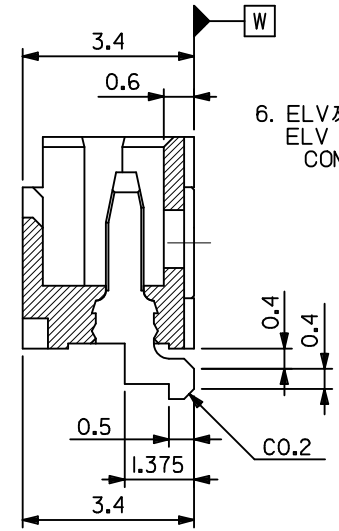


53261-****	WAFER ASSY	MODEL NO./MATERIAL NO.
50079-****	TERMINAL	
51021-****	HOUSING	

RELEASED EC NO: J2006-2426 DRWN: YAOYAGI 2006/02/02 CHKD: YMAEDA 2006/02/03 APPR: NUKITA 2006/02/07 REV 0	DESCRIPTION	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION		
		10 UNDER	± ---	DRAWN BY Y. AOYAGI	DATE 2006/01/30	TITLE 1.25 W-TO-B CONN. 51021,53261 MATING CROSS SECTION				
		10 OVER 30 UNDER	± ---	CHECKED BY Y. MAEDA	DATE 2006/01/30					
		30 OVER	± ---	APPROVED BY N. UKITA	DATE 2006/01/30	MOLEX INCORPORATED				
		ANGULAR ± --- °		MATERIAL NO.			DOCUMENT NO.			SHEET NO.
		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SEE CHART			SD-51021-002			1 OF 1
	REV	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION								



参考基板レイアウト
RECOMMENDED P.C.BOARD PATTERN DIM.(REF.)
(SCALE 5:1)



[断面図]
[CROSS SECTION]

6. ELV及びRoHS適合品
ELV AND RoHS
COMPLIANT.

注記 NOTES

1. 嵌合相手: 51021 シリズ
MATES WITH: 51021 SERIES
2. 材質 MATERIAL
ウェハー : NYLON46, UL94V-0
ピン : リン青銅
PIN : PHOS-BRO
: 銅メッキ 1.0マイクロメートル以上
: TIN 1.0 MICROMETER MINIMUM
: ニッケル下地 1.0マイクロメートル以上
: NICKEL(UNDER PLATING) 1.0 MICROMETER MINIMUM
金具 : リン青銅
FITTING NAIL : PHOS-BRO
: 銅メッキ 1.0マイクロメートル以上
: TIN 1.0 MICROMETER MINIMUM
: ニッケル下地 1.0マイクロメートル以上
: NICKEL(UNDER PLATING) 1.0 MICROMETER MINIMUM
- △ ロック窓は2、3極は1箇所、4極以上は2箇所とする。
LOCKING WINDOW :
ONE PLACE FOR 2 AND 3 CKT. AND
TWO PLACES FOR MORE THAN 3 CKT.
4. ソルダテール部のスレ量及び金具(補強板)のスレ量は基準面 [W] に対し、上方向 0.05 MAX.、下方向に 0.1 MAX. とする。 [W]
OFFSET BETWEEN BASIS PLANE
TO SOLDER TAIL BOTTOM AND
FITTING NAIL BOTTOM :
UPPER SIDE : 0.05MAX.
LOWER SIDE : 0.1MAX.
5. 本製品は 53261-***10 の鉛フリー品である。
THIS PRODUCT IS LEAD FREE OF 53261-***10

26.4	26	23	21.8	20	53261-1719	17	
23.9	23.5	20.5	19.3	17.5	↗ -1519	15	
22.65	22.25	19.25	18.05	16.25	↗ -1419	14	
21.4	21	18	16.8	15	↗ -1319	13	
20.15	19.75	16.75	15.55	13.75	↗ -1219	12	
18.9	18.5	15.5	14.3	12.5	↗ -1119	11	
17.65	17.25	14.25	13.05	11.25	↗ -1019	10	
16.4	16	13	11.8	10	↗ -0919	9	
15.15	14.75	11.75	10.55	8.75	↗ -0819	8	
13.9	13.5	10.5	9.3	7.5	↗ -0719	7	
12.65	12.25	9.25	8.05	6.25	↗ -0619	6	
11.4	11	8	6.8	5	↗ -0519	5	
10.15	9.75	6.75	5.55	3.75	↘ -0419	4	
8.9	8.5	5.5	4.3	2.5	↘ -0319	3	
9	7.65	7.25	4.25	3.05	1.25	53261-0219	2
1.	E	D	C	B	A	MATERIAL. NO.	極數 CKT.

REVISED EC NO: J2012-1315 2012/04/16 DRWN: NITO 2012/04/16 CHKD: KASAKAWA 2012/04/16 APPR: Y010 2012/04/16	DESCRIPTION REV	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE 10:1		DESIGN UNITS METRIC		THIRD ANGLE PROJECTION	
		10 UNDER	±0.2	DRAWN BY HSHIMABU	DATE 04/02/06	TITLE 1.25 WIRE TO BOARD WAFER ASS FOR SMT				SHEET NO. 1 OF 1	
		10 OVER 30 UNDER	±0.25	CHECKED BY KTOJO	DATE 04/02/06						
		30 OVER	±0.3	APPROVED BY MSASAO	DATE 04/02/06						
		ANGULAR ±3 °		MATERIAL NO.		DOCUMENT NO.					
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SEE DRAWING		SD-53261-024							
SIZE A3		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION									

